

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1. -20. Canceled
21. (New) A semiconductor device manufacturing method comprising:
preparing an assembling apparatus comprising a cover, having an opening therein,
provided on a setting base comprising a heating function;
setting a plate-like substrate having conductive patterns mounted on the setting base; and
mounting a semiconductor chip to the substrate or wire-bonding electrodes of the
semiconductor chip to the conductive patterns through the opening,
wherein an illumination is disposed above the opening and a blowing device is provided
at a periphery part of the illumination in order to prevent a fluctuation of an inert gas generated
by the heating function from entering inside the illumination upon mounting or wire-bonding the
semiconductor chip.
22. (New) The semiconductor device manufacturing method of claim 15, wherein the
blowing device provides a blow current to escape the fluctuation.
23. (New) The semiconductor device manufacturing method of claim 16, wherein the
fluctuation escapes in a horizontal direction.
24. (New) The semiconductor device manufacturing method of claim 15, wherein a part
of the cover is formed of a clamper.

25. (New) The semiconductor device manufacturing method of claim 18, wherein the inert gas is blown inside the cover through the clamper.

26. (New) The semiconductor device manufacturing method of claim 15, wherein the inert gas comprises nitrogen gas.

27. (New) The semiconductor device manufacturing method of claim 15, wherein a lens barrel is disposed above the illumination.

28. (New) The semiconductor device manufacturing method of claim 21, wherein a pattern recognition camera is disposed in the lens barrel.